

**Notice of References Cited**

Application/Control No.

10/054,697

Applicant(s)/Patent Under

Reexamination

WALITZKI ET AL.

Examiner

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Art Unit

2822

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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.